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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	74
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640e-3t100c

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

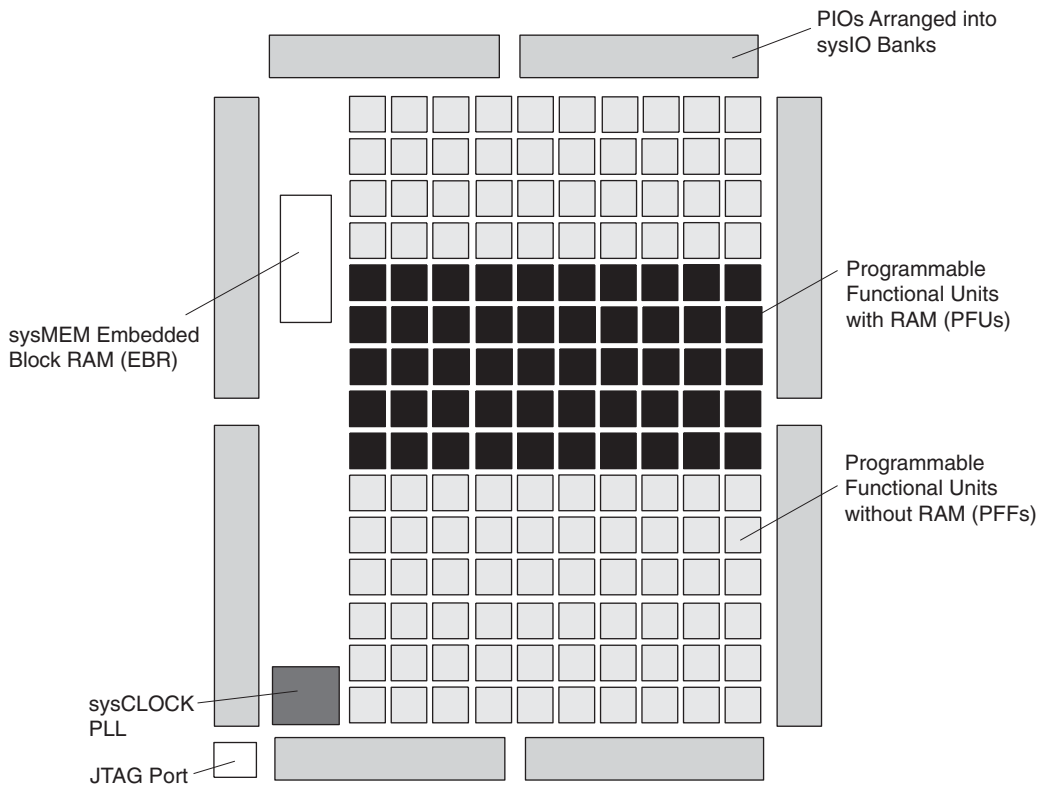
In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

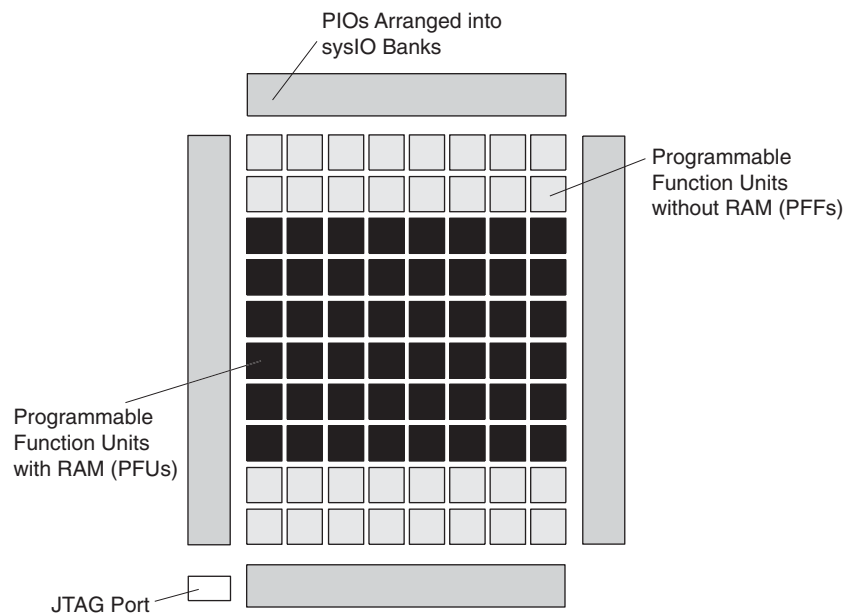
Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

Figure 2-1. Top View of the MachXO1200 Device¹



1. Top view of the MachXO2280 device is similar but with higher LUT count, two PLLs, and three EBR blocks.

Figure 2-2. Top View of the MachXO640 Device



Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
 - A greater-than-or-equal-to B
 - A not-equal-to B
 - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

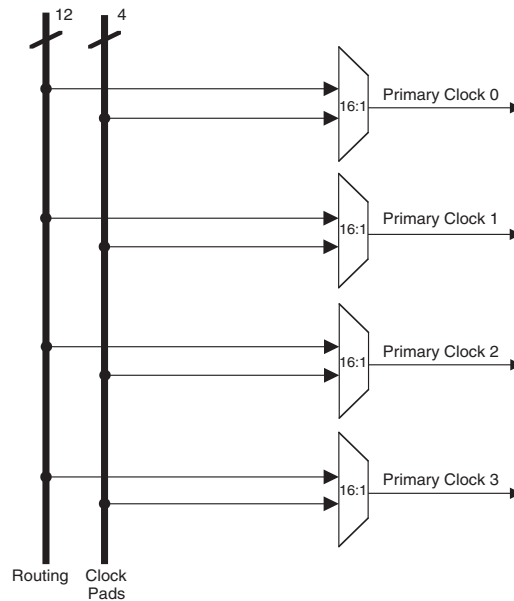
Note: SPR = Single Port RAM, DPR = Dual Port RAM

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock/Control Distribution Network

The MachXO family of devices provides global signals that are available to all PFUs. These signals consist of four primary clocks and four secondary clocks. Primary clock signals are generated from four 16:1 muxes as shown in Figure 2-7 and Figure 2-8. The available clock sources for the MachXO256 and MachXO640 devices are four dual function clock pins and 12 internal routing signals. The available clock sources for the MachXO1200 and MachXO2280 devices are four dual function clock pins, up to nine internal routing signals and up to six PLL outputs.

Figure 2-7. Primary Clocks for MachXO256 and MachXO640 Devices



PIO Groups

On the MachXO devices, PIO cells are assembled into two different types of PIO groups, those with four PIO cells and those with six PIO cells. PIO groups with four IOs are placed on the left and right sides of the device while PIO groups with six IOs are placed on the top and bottom. The individual PIO cells are connected to their respective sysIO buffers and PADs.

On all MachXO devices, two adjacent PIOs can be joined to provide a complementary Output driver pair. The I/O pin pairs are labeled as "T" and "C" to distinguish between the true and complement pins.

The MachXO1200 and MachXO2280 devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. In addition, half of the PIO pairs on the left and right sides of these devices can be configured as LVDS transmit/receive pairs. PIOs on the top of these larger devices also provide PCI support.

Figure 2-15. Group of Four Programmable I/O Cells

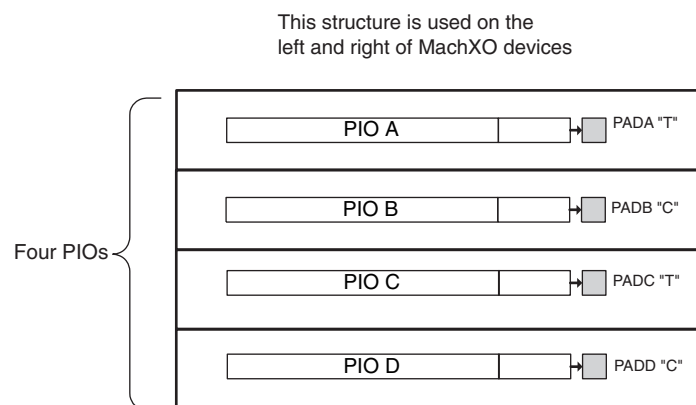
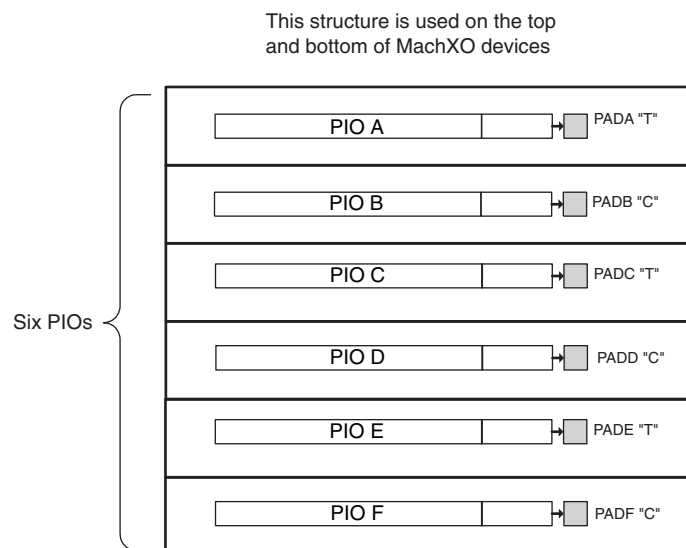


Figure 2-16. Group of Six Programmable I/O Cells



PIO

The PIO blocks provide the interface between the sysIO buffers and the internal PFU array blocks. These blocks receive output data from the PFU array and a fast output data signal from adjacent PFUs. The output data and fast

Figure 2-20. MachXO640 Banks

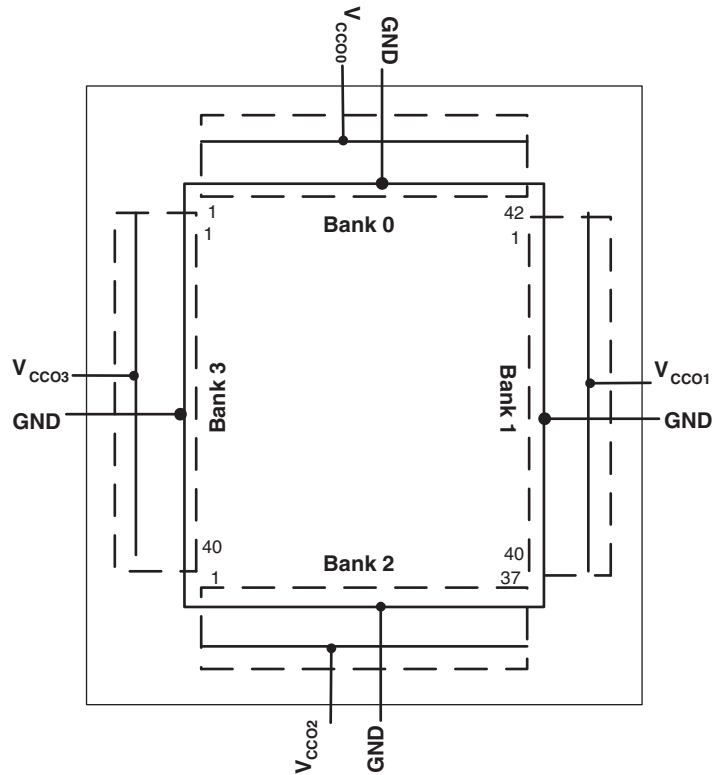
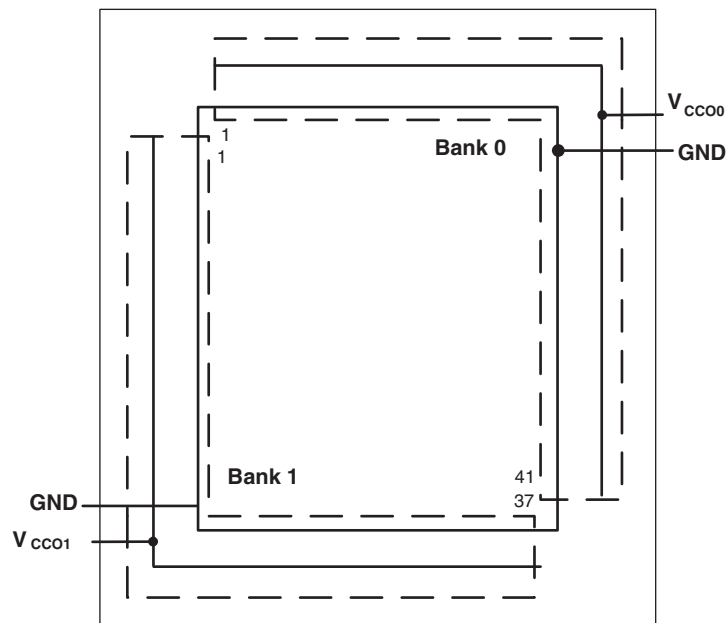


Figure 2-21. MachXO256 Banks



Hot Socketing

The MachXO devices have been carefully designed to ensure predictable behavior during power-up and power-down. Leakage into I/O pins is controlled to within specified limits. This allows for easy integration with the rest of

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Table 3-1. LVDS DC Conditions

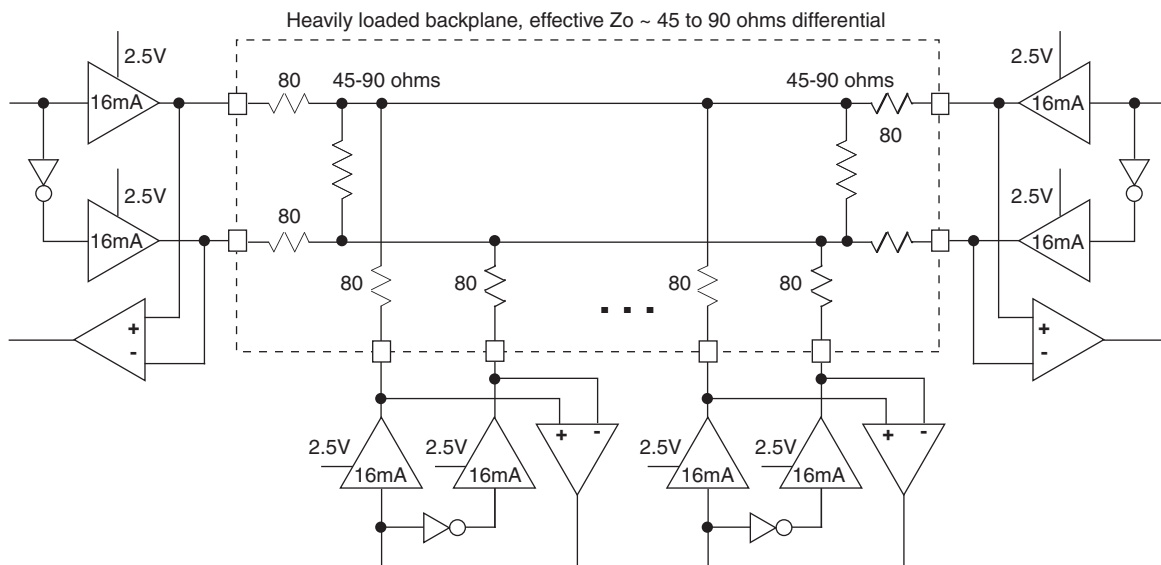
Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z _{OUT}	Output impedance	20	Ω
R _S	Driver series resistor	294	Ω
R _P	Driver parallel resistor	121	Ω
R _T	Receiver termination	100	Ω
V _{OH}	Output high voltage	1.43	V
V _{OL}	Output low voltage	1.07	V
V _{OD}	Output differential voltage	0.35	V
V _{CM}	Output common mode voltage	1.25	V
Z _{BACK}	Back impedance	100	Ω
I _{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example



MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTTL33	LVTTTL	0.01	0.01	0.01	ns
LVC MOS33	LVC MOS 3.3	0.01	0.01	0.01	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.08	0.10	ns
LVC MOS15	LVC MOS 1.5	0.14	0.17	0.19	ns
LVC MOS12	LVC MOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.04	0.04	0.05	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.07	0.08	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.50	0.60	0.70	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVC MOS33_14mA	LVC MOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_14mA	LVC MOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVC MOS18_14mA	LVC MOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.
 2. LVC MOS timing is measured with the load specified in Switching Test Conditions table.
 3. All other standards tested according to the appropriate specifications.
 4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.
- Rev. A 0.19

Switching Test Conditions

Figure 3-6 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-6. Output Test Load, LVTTTL and LVCMOS Standards

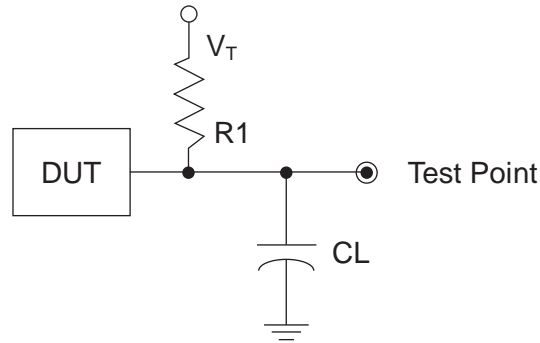


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTTL and LVCMOS settings (L -> H, H -> L)	∞	0pF	LVTTTL, LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVTTTL and LVCMOS 3.3 (Z -> H)	188	0pF	1.5	V_{OL}
LVTTTL and LVCMOS 3.3 (Z -> L)				V_{OH}
Other LVCMOS (Z -> H)			$V_{CCIO}/2$	V_{OL}
Other LVCMOS (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVTTTL + LVCMOS (H -> Z)			$V_{OH} - 0.15$	V_{OL}
LVTTTL + LVCMOS (L -> Z)			$V_{OL} - 0.15$	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
4	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
5	PL4B	7			PL4B	7		
6	VCCIO7	7			VCCIO7	7		
7	PL6A	7		T*	PL7A	7		T*
8	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
9	GND	-			GND	-		
10	PL7C	7		T	PL9C	7		T
11	PL7D	7		C	PL9D	7		C
12	PL8C	7		T	PL10C	7		T
13	PL8D	7		C	PL10D	7		C
14	PL9C	6			PL11C	6		
15	PL10A	6		T*	PL13A	6		T*
16	PL10B	6		C*	PL13B	6		C*
17	VCC	-			VCC	-		
18	PL11B	6			PL14D	6		C
19	PL11C	6	TSALL		PL14C	6	TSALL	T
20	VCCIO6	6			VCCIO6	6		
21	PL13C	6			PL16C	6		
22	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
23	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
24	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
25	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
26**	GNDIO6 GNDIO5	-			GNDIO6 GNDIO5	-		
27	VCCIO5	5			VCCIO5	5		
28	TMS	5	TMS		TMS	5	TMS	
29	TCK	5	TCK		TCK	5	TCK	
30	PB3B	5			PB3B	5		
31	PB4A	5		T	PB4A	5		T
32	PB4B	5		C	PB4B	5		C
33	TDO	5	TDO		TDO	5	TDO	
34	TDI	5	TDI		TDI	5	TDI	
35	VCC	-			VCC	-		
36	VCCAUX	-			VCCAUX	-		
37	PB6E	5		T	PB8E	5		T
38	PB6F	5		C	PB8F	5		C
39	PB7B	4	PCLK4_1****		PB10F	4	PCLK4_1****	
40	PB7F	4	PCLK4_0****		PB10B	4	PCLK4_0****	
41	GND	-			GND	-		

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B9	PT7B	0		C	B9	PT9B	1		C	B9	PT12D	1		C
A9	PT7A	0		T	A9	PT9A	1		T	A9	PT12C	1		T
A8	PT6B	0	PCLK0_1***	C	A8	PT7D	1	PCLK1_1***		A8	PT10B	1	PCLK1_1***	
B8	PT6A	0		T	B8	PT7B	1			B8	PT9D	1		
C8	PT5B	0	PCLK0_0***	C	C8	PT6F	0	PCLK1_0***		C8	PT9B	1	PCLK1_0***	
B7	PT5A	0		T	B7	PT6D	0			B7	PT8D	0		
A7	VCCAUX	-			A7	VCCAUX	-			A7	VCCAUX	-		
C7	VCC	-			C7	VCC	-			C7	VCC	-		
A6	PT4D	0		C	A6	PT5D	0		C	A6	PT7B	0		C
B6	PT4C	0		T	B6	PT5C	0		T	B6	PT7A	0		T
C6	PT3F	0		C	C6	PT5B	0		C	C6	PT6D	0		
B5	PT3E	0		T	B5	PT5A	0		T	B5	PT6E	0		T
A5	PT3D	0			A5	PT4B	0			A5	PT6F	0		C
B4	GNDIO0	0			B4	GNDIO0	0			B4	GNDIO0	0		
A4	PT3B	0			A4	PT3D	0		C	A4	PT4B	0		C
C4	PT2F	0			C4	PT3C	0		T	C4	PT4A	0		T
A3	PT2D	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2C	0		T	A2	PT2B	0		C	A2	PT2B	0		C
B3	PT2B	0		C	B3	PT3A	0		T	B3	PT3A	0		T
A1	PT2A	0		T	A1	PT2A	0		T	A1	PT2A	0		T
F1	GND	-			F1	GND	-			F1	GND	-		
P9	GND	-			P9	GND	-			P9	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
C9	GND	-			C9	GND	-			C9	GND	-		
C5	VCCIO0	0			C5	VCCIO0	0			C5	VCCIO0	0		
B11	VCCIO0	0			B11	VCCIO1	1			B11	VCCIO1	1		
E12	VCCIO1	1			E12	VCCIO2	2			E12	VCCIO2	2		
L12	VCCIO1	1			L12	VCCIO3	3			L12	VCCIO3	3		
M10	VCCIO2	2			M10	VCCIO4	4			M10	VCCIO4	4		
N2	VCCIO2	2			N2	VCCIO5	5			N2	VCCIO5	5		
D2	VCCIO3	3			D2	VCCIO7	7			D2	VCCIO7	7		
K3	VCCIO3	3			K3	VCCIO6	6			K3	VCCIO6	6		

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs are single-ended.

**LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections:
 144 TQFP**

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	3		T	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2C	3		T	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL2B	3		C	PL3A	7		T*	PL3A	7		T*
4	PL3A	3		T	PL3B	7		C*	PL3B	7		C*
5	PL2D	3		C	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
6	PL3B	3		C	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
7	PL3C	3		T	PL4A	7		T*	PL4A	7		T*
8	PL3D	3		C	PL4B	7		C*	PL4B	7		C*
9	PL4A	3			PL4C	7			PL4C	7		
10	VCCIO3	3			VCCIO7	7			VCCIO7	7		
11	GNDIO3	3			GNDIO7	7			GNDIO7	7		
12	PL4D	3			PL5C	7			PL6C	7		
13	PL5A	3		T	PL6A	7		T*	PL7A	7		T*
14	PL5B	3	GSRN	C	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
15	PL5D	3			PL6D	7			PL7D	7		
16	GND	-			GND	-			GND	-		
17	PL6C	3		T	PL7C	7		T	PL9C	7		T
18	PL6D	3		C	PL7D	7		C	PL9D	7		C
19	PL7A	3		T	PL10A	6		T*	PL13A	6		T*
20	PL7B	3		C	PL10B	6		C*	PL13B	6		C*
21	VCC	-			VCC	-			VCC	-		
22	PL8A	3		T	PL11A	6		T*	PL13D	6		
23	PL8B	3		C	PL11B	6		C*	PL14D	6		C
24	PL8C	3	TSALL		PL11C	6	TSALL		PL14C	6	TSALL	T
25	PL9C	3		T	PL12B	6			PL15B	6		
26	VCCIO3	3			VCCIO6	6			VCCIO6	6		
27	GNDIO3	3			GNDIO6	6			GNDIO6	6		
28	PL9D	3		C	PL13D	6			PL16D	6		
29	PL10A	3		T	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
30	PL10B	3		C	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
31	PL10C	3		T	PL14C	6		T	PL17C	6		T
32	PL11A	3		T	PL14D	6		C	PL17D	6		C
33	PL10D	3		C	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
34	PL11C	3		T	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
35	PL11B	3		C	PL16A	6		T	PL19A	6		T
36	PL11D	3		C	PL16B	6		C	PL19B	6		C
37	GNDIO2	2			GNDIO5	5			GNDIO5	5		
38	VCCIO2	2			VCCIO5	5			VCCIO5	5		
39	TMS	2	TMS		TMS	5	TMS		TMS	5	TMS	
40	PB2C	2			PB2C	5		T	PB2A	5		T
41	PB3A	2		T	PB2D	5		C	PB2B	5		C
42	TCK	2	TCK		TCK	5	TCK		TCK	5	TCK	
43	PB3B	2		C	PB3A	5		T	PB3A	5		T
44	PB3C	2		T	PB3B	5		C	PB3B	5		C
45	PB3D	2		C	PB4A	5		T	PB4A	5		T
46	PB4A	2		T	PB4B	5		C	PB4B	5		C
47	TDO	2	TDO		TDO	5	TDO		TDO	5	TDO	
48	PB4B	2		C	PB4D	5			PB4D	5		
49	PB4C	2		T	PB5A	5		T	PB5A	5		T
50	PB4D	2		C	PB5B	5		C	PB5B	5		C

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		C	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2		C	PR4D	2		C
104	PR2D	1		C	PR3C	2		T	PR4C	2		T
105	PR3A	1		T	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2		C	PR3B	2		C*
108	PR2A	1		T	PR2A	2		T	PR3A	2		T*
109	PT9F	0		C	PT11D	1		C	PT16D	1		C
110	PT9D	0		C	PT11C	1		T	PT16C	1		T
111	PT9E	0		T	PT11B	1		C	PT16B	1		C
112	PT9B	0		C	PT11A	1		T	PT16A	1		T
113	PT9C	0		T	PT10F	1		C	PT15D	1		C
114	PT9A	0		T	PT10E	1		T	PT15C	1		T
115	PT8C	0			PT10D	1		C	PT14B	1		C
116	PT8B	0		C	PT10C	1		T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		T	PT9F	1		C	PT12F	1		C
120	PT7E	0			PT9E	1		T	PT12E	1		T
121	PT7C	0			PT9B	1		C	PT12D	1		C
122	PT7A	0			PT9A	1		T	PT12C	1		T
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1		C	PT9D	1		C
126	PT5C	0			PT7A	1		T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		C	PT7B	0		C
131	PT4B	0		C	PT5C	0		T	PT7A	0		T
132	PT4A	0		T	PT5B	0		C	PT6D	0		
133	PT3F	0			PT5A	0		T	PT6E	0		T
134	PT3D	0			PT4B	0			PT6F	0		C
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		C	PT3D	0		C	PT4B	0		T
138	PT2F	0		C	PT3C	0		T	PT4A	0		C
139	PT3A	0		T	PT3B	0		C	PT3B	0		C
140	PT2D	0		C	PT3A	0		T	PT3A	0		T
141	PT2E	0		T	PT2D	0		C	PT2D	0		C
142	PT2B	0		C	PT2C	0		T	PT2C	0		T
143	PT2C	0		T	PT2B	0		C	PT2B	0		C
144	PT2A	0		T	PT2A	0		T	PT2A	0		T

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs are single-ended.

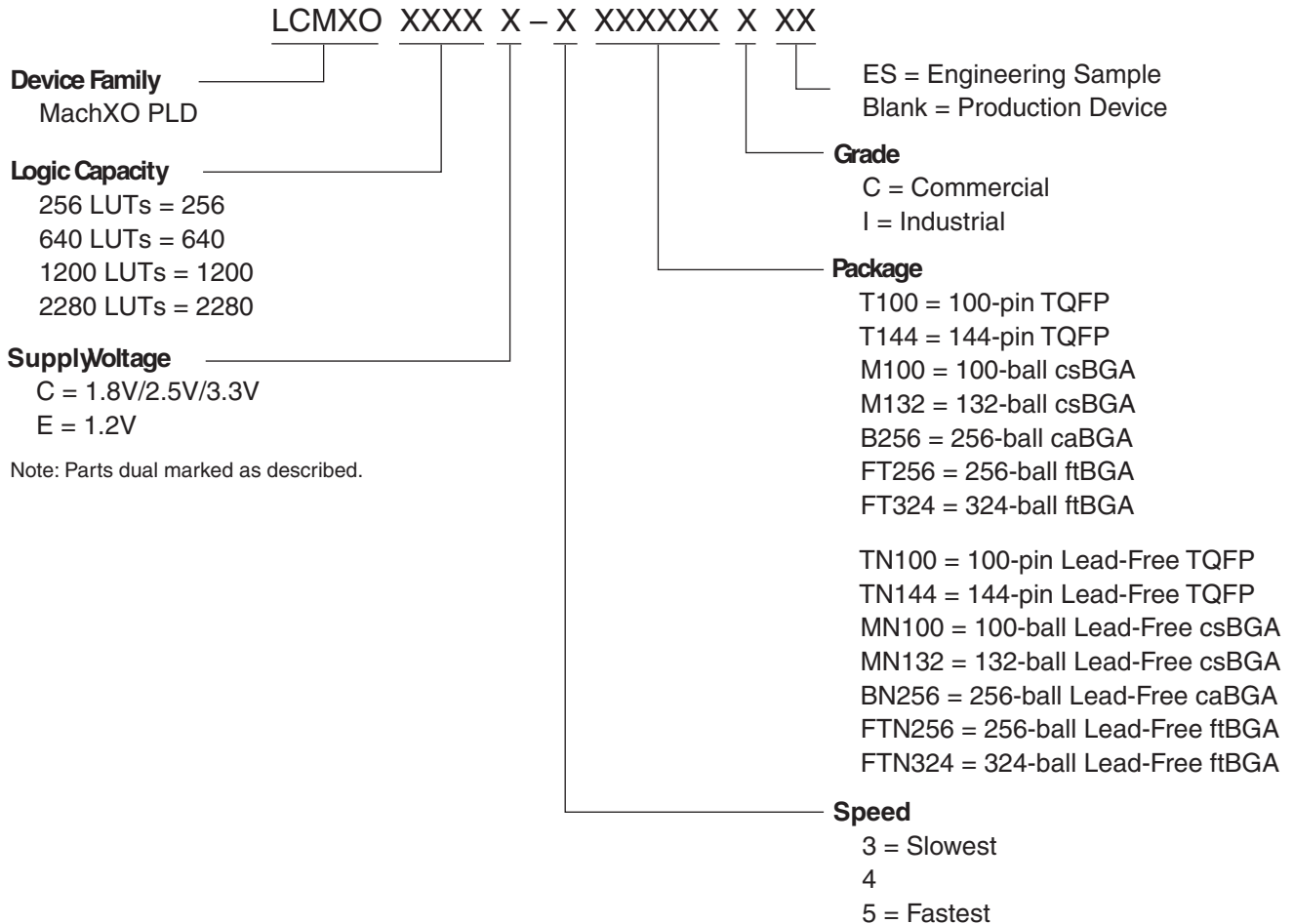
**LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections:
 256 caBGA / 256 ftBGA (Cont.)**

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J4	PL8A	3		T	J4	PL13A	6		T*	J4	PL16A	6		T*
J5	PL8B	3		C	J5	PL13B	6		C*	J5	PL16B	6		C*
R1	PL11A	3		T	R1	PL13C	6		T	R1	PL16C	6		T
R2	PL11B	3		C	R2	PL13D	6		C	R2	PL16D	6		C
-	-	-			-	-	-			GND	GND	-		
K5	NC				K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	T*
K4	NC				K4	PL14B	6	LLM0_PLCC_FB_A	C*	K4	PL17B	6	LLM0_PLCC_FB_A	C*
L5	PL10C	3		T	L5	PL14C	6		T	L5	PL17C	6		T
L4	PL10D	3		C	L4	PL14D	6		C	L4	PL17D	6		C
M5	NC				M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	T*
M4	NC				M4	PL15B	6	LLM0_PLCC_IN_A	C*	M4	PL18B	6	LLM0_PLCC_IN_A	C*
N4	PL11C	3		T	N4	PL16A	6		T	N4	PL19A	6		T
N3	PL11D	3		C	N3	PL16B	6		C	N3	PL19B	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
P4	TMS	2	TMS		P4	TMS	5	TMS		P4	TMS	5	TMS	
P2	NC				P2	PB2A	5		T	P2	PB2A	5		T
P3	NC				P3	PB2B	5		C	P3	PB2B	5		C
N5	NC				N5	PB2C	5		T	N5	PB2C	5		T
R3	TCK	2	TCK		R3	TCK	5	TCK		R3	TCK	5	TCK	
N6	NC				N6	PB2D	5		C	N6	PB2D	5		C
T2	PB2A	2		T	T2	PB3A	5		T	T2	PB3A	5		T
T3	PB2B	2		C	T3	PB3B	5		C	T3	PB3B	5		C
R4	PB2C	2		T	R4	PB3C	5		T	R4	PB3C	5		T
R5	PB2D	2		C	R5	PB3D	5		C	R5	PB3D	5		C
P5	PB3A	2		T	P5	PB4A	5		T	P5	PB4A	5		T
P6	PB3B	2		C	P6	PB4B	5		C	P6	PB4B	5		C
T5	PB3C	2		T	T5	PB4C	5		T	T5	PB4C	5		T
M6	TDO	2	TDO		M6	TDO	5	TDO		M6	TDO	5	TDO	
T4	PB3D	2		C	T4	PB4D	5		C	T4	PB4D	5		C
R6	PB4A	2		T	R6	PB5A	5		T	R6	PB5A	5		T
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
T6	PB4B	2		C	T6	PB5B	5		C	T6	PB5B	5		C
N7	TDI	2	TDI		N7	TDI	5	TDI		N7	TDI	5	TDI	
T8	PB4C	2		T	T8	PB5C	5		T	T8	PB6A	5		T
T7	PB4D	2		C	T7	PB5D	5		C	T7	PB6B	5		C
M7	NC				M7	PB6A	5		T	M7	PB7C	5		T
M8	NC				M8	PB6B	5		C	M8	PB7D	5		C
T9	VCCAUX	-			T9	VCCAUX	-			T9	VCCAUX	-		
R7	PB4E	2		T	R7	PB6C	5		T	R7	PB8C	5		T
R8	PB4F	2		C	R8	PB6D	5		C	R8	PB8D	5		C
-	-				VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
-	-				GND	GNDIO5	5			GND	GNDIO5	5		
P7	PB5C	2		T	P7	PB6E	5		T	P7	PB9A	4		T
P8	PB5D	2		C	P8	PB6F	5		C	P8	PB9B	4		C
N8	PB5A	2		T	N8	PB7A	4		T	N8	PB10E	4		T
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***	C
P10	PB7B	2		C	P10	PB7D	4		C	P10	PB10D	4		C
P9	PB7A	2		T	P9	PB7C	4		T	P9	PB10C	4		T
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***	C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

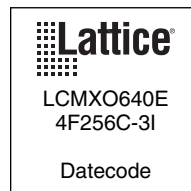
LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

Part Number Description



Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device. For example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade. The slowest commercial speed grade does not have industrial markings. The markings appears as follows:



Dual Mark

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100C	1200	1.2V	73	-3	TQFP	100	COM
LCMXO1200E-4T100C	1200	1.2V	73	-4	TQFP	100	COM
LCMXO1200E-5T100C	1200	1.2V	73	-5	TQFP	100	COM
LCMXO1200E-3T144C	1200	1.2V	113	-3	TQFP	144	COM
LCMXO1200E-4T144C	1200	1.2V	113	-4	TQFP	144	COM
LCMXO1200E-5T144C	1200	1.2V	113	-5	TQFP	144	COM
LCMXO1200E-3M132C	1200	1.2V	101	-3	csBGA	132	COM
LCMXO1200E-4M132C	1200	1.2V	101	-4	csBGA	132	COM
LCMXO1200E-5M132C	1200	1.2V	101	-5	csBGA	132	COM
LCMXO1200E-3B256C	1200	1.2V	211	-3	caBGA	256	COM
LCMXO1200E-4B256C	1200	1.2V	211	-4	caBGA	256	COM
LCMXO1200E-5B256C	1200	1.2V	211	-5	caBGA	256	COM
LCMXO1200E-3FT256C	1200	1.2V	211	-3	ftBGA	256	COM
LCMXO1200E-4FT256C	1200	1.2V	211	-4	ftBGA	256	COM
LCMXO1200E-5FT256C	1200	1.2V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100C	2280	1.2V	73	-3	TQFP	100	COM
LCMXO2280E-4T100C	2280	1.2V	73	-4	TQFP	100	COM
LCMXO2280E-5T100C	2280	1.2V	73	-5	TQFP	100	COM
LCMXO2280E-3T144C	2280	1.2V	113	-3	TQFP	144	COM
LCMXO2280E-4T144C	2280	1.2V	113	-4	TQFP	144	COM
LCMXO2280E-5T144C	2280	1.2V	113	-5	TQFP	144	COM
LCMXO2280E-3M132C	2280	1.2V	101	-3	csBGA	132	COM
LCMXO2280E-4M132C	2280	1.2V	101	-4	csBGA	132	COM
LCMXO2280E-5M132C	2280	1.2V	101	-5	csBGA	132	COM
LCMXO2280E-3B256C	2280	1.2V	211	-3	caBGA	256	COM
LCMXO2280E-4B256C	2280	1.2V	211	-4	caBGA	256	COM
LCMXO2280E-5B256C	2280	1.2V	211	-5	caBGA	256	COM
LCMXO2280E-3FT256C	2280	1.2V	211	-3	ftBGA	256	COM
LCMXO2280E-4FT256C	2280	1.2V	211	-4	ftBGA	256	COM
LCMXO2280E-5FT256C	2280	1.2V	211	-5	ftBGA	256	COM
LCMXO2280E-3FT324C	2280	1.2V	271	-3	ftBGA	324	COM
LCMXO2280E-4FT324C	2280	1.2V	271	-4	ftBGA	324	COM
LCMXO2280E-5FT324C	2280	1.2V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3TN100C	1200	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200E-4TN100C	1200	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200E-5TN100C	1200	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200E-3TN144C	1200	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200E-4TN144C	1200	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200E-5TN144C	1200	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200E-3MN132C	1200	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200E-4MN132C	1200	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200E-5MN132C	1200	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200E-3BN256C	1200	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200E-4BN256C	1200	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200E-5BN256C	1200	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200E-3FTN256C	1200	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200E-4FTN256C	1200	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200E-5FTN256C	1200	1.2V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3TN100C	2280	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO2280E-4TN100C	2280	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO2280E-5TN100C	2280	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO2280E-3TN144C	2280	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO2280E-4TN144C	2280	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO2280E-5TN144C	2280	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO2280E-3MN132C	2280	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO2280E-4MN132C	2280	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO2280E-5MN132C	2280	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO2280E-3BN256C	2280	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO2280E-4BN256C	2280	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO2280E-5BN256C	2280	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO2280E-3FTN256C	2280	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO2280E-4FTN256C	2280	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO2280E-5FTN256C	2280	1.2V	211	-5	Lead-Free ftBGA	256	COM
LCMXO2280E-3FTN324C	2280	1.2V	271	-3	Lead-Free ftBGA	324	COM
LCMXO2280E-4FTN324C	2280	1.2V	271	-4	Lead-Free ftBGA	324	COM
LCMXO2280E-5FTN324C	2280	1.2V	271	-5	Lead-Free ftBGA	324	COM

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timing updated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
Pin Information Summary updated.			
Power Supply and NC Connection table has been updated.			
Logic Signal Connection section has been updated to include all devices/packages.			
Ordering Information	Part Number Description section has been updated.		
	Ordering Part Number section has been updated (added LCMXO256C/LCMXO640C "4W").		
Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.		
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.